

APPROVAL SHEET

MULTILAYER CHIP VARISTOR

For Surge Protection

Size 0805

VZ0805 Series

*Contents in this sheet are subject to change without prior notice.



DESCRIPTION

Walsin Multilayer Chip Varistor is a family of Transient Voltage Surge Suppression products. Today, electronic circuits are becoming smaller and more sentive to external interference. Walsin Multilayer Chip Varistor is designed to protect components from destruction of transients and ESD(Electronic Static Discharge). The wide operating voltage and energy rage make Walsin Multilayer Chip Varistor suitable for numerous applications on I/O protection, Vcc protection, Keyboard protection, LCD protection, Sensor protection...etc. The Walsin Chip Varistor is manufactured by Multilayer fabrication technology providing excellent voltage clamping ability and is supplied in leadless, surface mount form, compatible with modern reflow and wave soldering procedures.

FEATURES

- 1. Multilayer fabrication technology
- 2. -40°C to 125°C operating temperature Range
- 3. Operating voltage range $V_{M(DC)}$ at 5.5V ~ 38V
- 4. Able to withstand ESD test of IEC-61000-4-2
- 5. Bi-directional clamping characteristic

APPLICATIONS

- 1. Protection of cellular phones, PDA, High Speed Data Line...etc.
- 2. ESD Protection for components sensitive to IEC 61000-4-2, Provides Circuit Board Transient Voltage Protection for Transistors.
- Protection of Video & Audio Ports.

DIMENSIONS

Figure	Symbol	VZ0805 Series
Ts	L	2.00 ± 0.20 mm
	W	1.25 ± 0.20 mm
W Ts T	Т	1.20 mm (max.)
Wasin	Ts	0.50 ± 0.30 mm

^{*}Terminal electrode: Ni / Sn electrode



DEVICE RATING AND SPECIFICATIONS

		MAX	IMUM RATI	SPECIFICATIONS				
Part Number	Max. Continuous Working Voltage		Maximum Non- Repetitive Surge Current	Maximum Non- Repetitive Surge Energy	Max. Claming Voltage at Specified Current	Nominal Voltage		Typical Capacitance
			(8/20 μ s)	(10/1000 μ s)	(8/20 μ s)	At 1mA (D	At 1mA (DC) Current	
	V _{M(DC)}	V _{M(AC)}	I _{TM}	W_{TM}	Vc	$V_{N(DC)}Min.$	V _{N(DC)} Max.	С
	(V)	(V)	(A)	(J)	(V)	(V)	(V)	(pF)
VZ0805M050AGTN	5.5	4	80	0.1	22 at 1A	7.8	12	500
VZ0805M090AGTN	9	6	80	0.2	30 at 1A	10.8	18	420
VZ0805M110AGTN	11	8	100	0.3	32 at 1A	14	20	360
VZ0805M140AGTN	14	11	100	0.1	38 at 1A	17.2	21	400
VZ0805M160AGTN	16	14	120	0.3	46 at 1A	22	28	400
VZ0805M180AGTN	18	14	120	0.3	44 at 1A	19.8	25.2	350
VZ0805M22LAGTN	22	17	30	0.1	54 at 1A	25	34	100
VZ0805M220AGTN	22	17	120	0.3	50 at 1A	24.3	30.7	400
VZ0805M260AGTN	26	20	100	0.4	56 at 1A	29.7	37.3	220
VZ0805M300AGTN	30	25	100	0.3	71 at 1A	35.1	43.9	250
VZ0805M380AGTN	38	30	100	0.3	81 at 1A	42.3	52.7	200
VZ0805M450AGTN	45	35	80	0.1	93 at 1A	55	61	170

STANDARD TESTING CONDITION

Unless otherwise specified

■ Temperature : 15 ~ 35°C■ Humidity : 25%RH ~ 85%RH

■ Atmospheric pressure: 86kPa ~ 106kPa



SPECIFICATION

1. Electrical Reliability

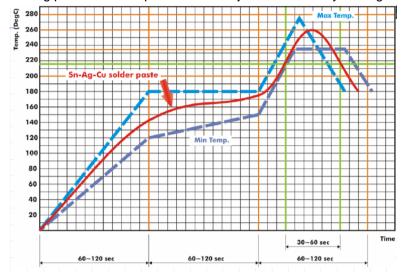
Test item	Test condition / Test method	Specification
High temperature storage	+125±3°C for 1000 hours Measurement to be made after keeping at room temp. for 24 ±2hr	△V at 1mA < 10%
Low temperature storage	-40±3°C for 1000 hours Measurement to be made after keeping at room temp. for 24 ±2h	△V at 1mA < 10%
Humidity storage	$40\pm2^{\circ}$ C , 90 ~95%RH for 500 hours Measurement to be made after keeping at room temp. for 24 $\pm2h$	△V at 1mA < 10%
Temperature cycles	Times: 5 cycles Step Temp.(°C) Time(min.) 1 -55 \pm 3 30 \pm 3 2 room temp. 2~3 3 +125 \pm 3°C 30 \pm 2 4 room temp. 2~3 Measurement to be made after keeping axt room temp. for 24 \pm 2h	△V at 1mA < 10%

2. Mechanical Reliability

Test item	Test condition / Test method	Specification
Solderability	Solder temp. : 230±5°C Immersion time : 2±0.5 sec Immersion and emersion rates : 25mm/s	Min 90% electrode shall be covered with solder.
Resistance to Soldering Heat	Pre-heating: 120~ 150°C , 60 sec Solder temp.: 260±5°C Immersion time: 10±1 sec Measurement to be made after keeping at room temp. for 24 ±2h	△V at 1mA < 10% Disappearance of electrode due to immersion into solder shall not exceed 25% of edges of each electrode.
Adhesive Strength of Termination	Solder chip on PCB and applied 0805/1206 Series: 10N(1Kgf) for 10 sec 0402/0603 Series: 5N(0.5Kgf) for 10 sec Chip varistor	No visible damage
Vibration	Solder chip on PCB. Frequency: 10 Hz~55 Hz~10 Hz (1min) Oscillation amplitude: 1.5 mm Times: 2 hrs in each of three perpendicular direction	No visible damage
Bending Test	The middle part of substrate shall be pressurized by means of the pressurizing rod at a rate of 1mm per second until the deflection becomes 1 mm and then the pressure shall be maintained for 5 sec	No visible damage △V at 1mA < 10%

SOLDERING CONDITION

Typical examples of soldering processes that provide reliable joints without any damage are given in figure below:



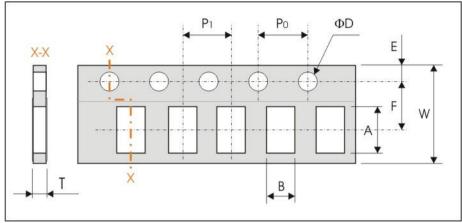
Infrared soldering profile

ORDERING CODE

VZ	0805	М	050	Α	G	Т	
Type Code	Chip Size	Style	Rated Voltage	Capacitance Tolerance	Termination	Packing	Internal Code
VZ: Walsin Varistor	0402 0603 0805	M: Multilayer	050 = 5.5V 070 = 7V 090 = 9V 140 = 14V 180 = 18V	A: Standard C: High Surge	G: Green Material	B: Bulk	Blank: None N: New item

PACKAGING

Paper Tape specifications (unit :mm) and Packaging quantity

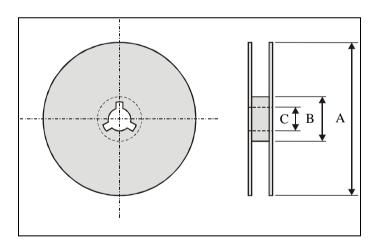


Label	А	В	E	F	ΦD
VZ0805 Series	2.30 ± 0.10	1.50 ± 0.10	1.75 ± 0.10	3.50 ± 0.05	1.55 ± 0.05

Label	P0	P1	Т	W	Quantity/Reel
VZ0805 Series	4.00 ± 0.10	4.00 ± 0.10	1.52 ± 0.05	8.00 ± 0.20	3Kpcs

[•] Tape Material : Paper tape.

Reel dimensions



Index	Α	В	С
Dimension (mm)	Ф178	Ф60.0	Ф13.5



CAUTION OF HANDLING

Limitation of Applications

Please contact us before using our products for the applications listed below which require especially high reliability for the prevention of defects, which might directly cause damage to the third party's life, body or property.

- (1) Aircraft equipment
- (2) Aerospace equipment
- (3) Undersea equipment
- (4) Medical equipment
- (5) Traffic signal equipment
- (6) Applications of similar complexity and /or reliability requirements to the applications listed in the above.

Storage condition

- (1) Products should be used in 6 months from the day of WALSIN outgoing inspection, which can be confirmed.
- (2) Storage environment condition.
 - Products should be storage in the warehouse on the following conditions.

■ Temperature : -10 to +40°C

Humidity : 30 to 70% relative humidity

- Don't keep products in corrosive gases such as sulfur. Chlorine gas or acid or it may cause oxidization of electrode, resulting in poor solderability.
- Products should be storage on the palette for the prevention of the influence from humidity, dust and son on.
- Products should be storage in the warehouse without heat shock, vibration, direct sunlight and so on.
- Products should be storage under the airtight packaged condition.